

## Product Change Notice (PCN)

**Date:** 08/23/2024

**PCN Number:** PCN-0456190R-01

To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: PJ-072C-SMT-TR

Reason(s) for Change: *Manufacturing Improvement processes*

Description of Change: *New Factory Location. Product re-engineered for improved manufacturability and production yield. See image below for reference and check CUI Devices website for updated drawing. Cosmetic differences may be visible but will not affect the form fit and function of the product.*

PREVIOUS CUI DEVICES DETAIL / IMAGE

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	copper alloy	gold (contact area) tin (remaining portion)
terminal 2	copper alloy	gold
shield	brass	nickel
housing	PA10T (UL94V-0)	black

NEW CUI DEVICES DETAIL / IMAGE

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	copper alloy	contact area: gold flash over nickel solder area: tin over nickel
terminal 2	copper alloy	gold flash over nickel
shield	brass	nickel
housing	PA10T (UL94V-0)	black

**SOLDERABILITY**

parameter	conditions/description	min	typ	max	units
refl storage	10-30°C, <70% humidity			40	°C
reflow soldering <sup>1</sup>	see reflow profile	255	260	265	°C
drying conditions <sup>2</sup>	parts in reel: bake at 100°C for 4 hours parts removed from reel: bake at 100°C for 4 hours				

Note: 1. CUI Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <60%.  
2. When resoldering from the tray, <168 hours.

Reflow profile graph showing temperature (°C) vs time (sec). The profile starts at 150°C, ramps up to 217°C (Tp-95), holds for 20-45 seconds, then ramps down to 150°C. A note indicates 8 minutes max at 217°C and 30-45 seconds at 150°C.

\* Time 25°C to Peak Temp. --- 8 Minutes Max.  
\* Time within 9°C of Actual Peak Temp. --- 30-45 Seconds

**SOLDERABILITY**

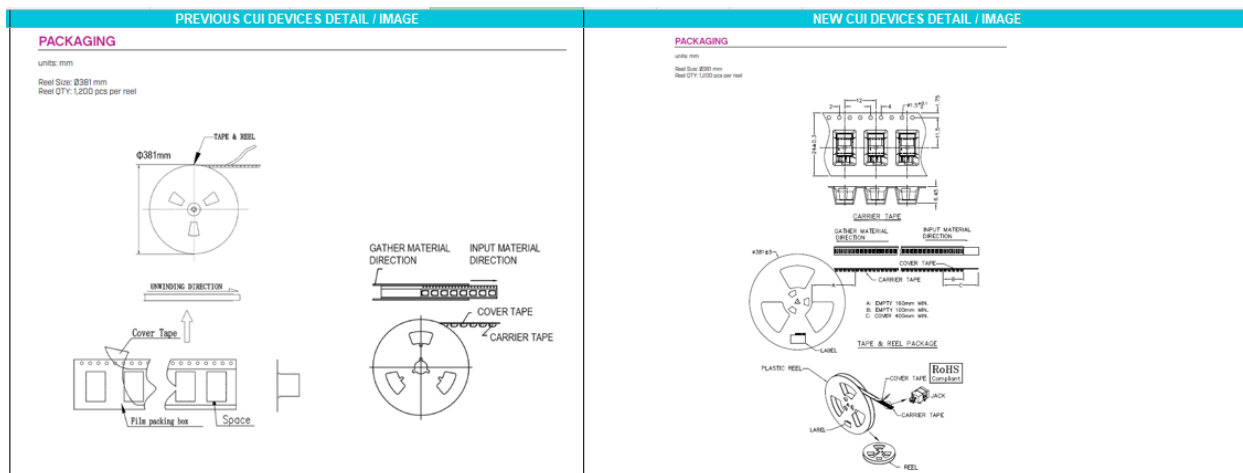
parameter	conditions/description	min	typ	max	units
refl storage	at relative humidity <60%			40	°C
reflow soldering <sup>1</sup>	see reflow profile	255	260	265	°C
drying conditions <sup>2</sup>	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

Note: 1. It is recommended to reflow within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <60%.  
2. When resoldering from the tray, <168 hours.

Reflow profile graph showing temperature (°C) vs time (sec). The profile starts at 150°C, ramps up to 217°C (Tp-95), holds for 20-45 seconds, then ramps down to 150°C. A note indicates 8 minutes max at 217°C and 30-45 seconds at 150°C.

F-723-001

Revision: A



Affected Date Code: All orders placed after **10/22/2024**

Product Availability: *Pertaining to market availability*

PCN Approval:

## Operations/Quality

Robert Davies

## Product Management

